METHOD OF CLEANING POST-CMP WAFER

Abstract of Disclosure

A post-CMP wafer is loaded into a buffer unit of a cleaning apparatus and is kept moist by adding a chemical. The post-CMP wafer is then loaded into a cleaning unit of the cleaning apparatus for performing the following cleaning process. The chemical added in the buffer unit is used to reduce the adhesion of benzotriazole (BTA) for improving the cleanliness of the post-CMP wafer.

(Figure 3)